

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	1224979
<b>Application Number:</b>	10715641
<b>Confirmation Number:</b>	4323
<b>Title of Invention:</b>	Raised solder-mask-defined (SMD) solder ball pads for a laminate electronic circuit board
<b>First Named Inventor:</b>	Tz-Cheng Chiu
<b>Customer Number:</b>	23494
<b>Filer:</b>	Yingsheng Tung/Jackie McBride
<b>Filer Authorized By:</b>	Yingsheng Tung
<b>Attorney Docket Number:</b>	TI-36052 (1962-07500)
<b>Receipt Date:</b>	28-SEP-2006
<b>Filing Date:</b>	18-NOV-2003
<b>Time Stamp:</b>	15:08:46
<b>Application Type:</b>	Utility
<b>International Application Number:</b>	

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Response to Election / Restriction Filed	TI-36052_ELECTION.pdf	2493	no	1

**Warnings:****Information:****Total Files Size (in bytes):**

2493

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**New Applications Under 35 U.S.C. 111**

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

**National Stage of an International Application under 35 U.S.C. 371**

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.